



ABSTRACT

A removable protective thermoformable coating for the packaging of electronic equipment. The coating includes a thermoplastic film and a microencapsulated silicone attached to one side of the film. The coating is vacuum formed and/or melted onto a component, releasing a one- or two-component silicone that forms a silicone layer. The silicone layer cures or hardens, and, together with the thermoplastic film, forms a protective coating. The coating may be removed or peeled off, as the silicone will preferentially adhere to the film.

Also, a method for applying a protective coating to a component. The component is contacted with a thermoplastic film having silicone microcapsules on the contacting side of the film. The film is heated and drawn down over the component by pressure or vacuum, breaking the silicone microcapsules and releasing liquid silicone. The silicone is allowed to cure and form a coating.